

The rise of monolithic sensors

From a few pixels to an experiment

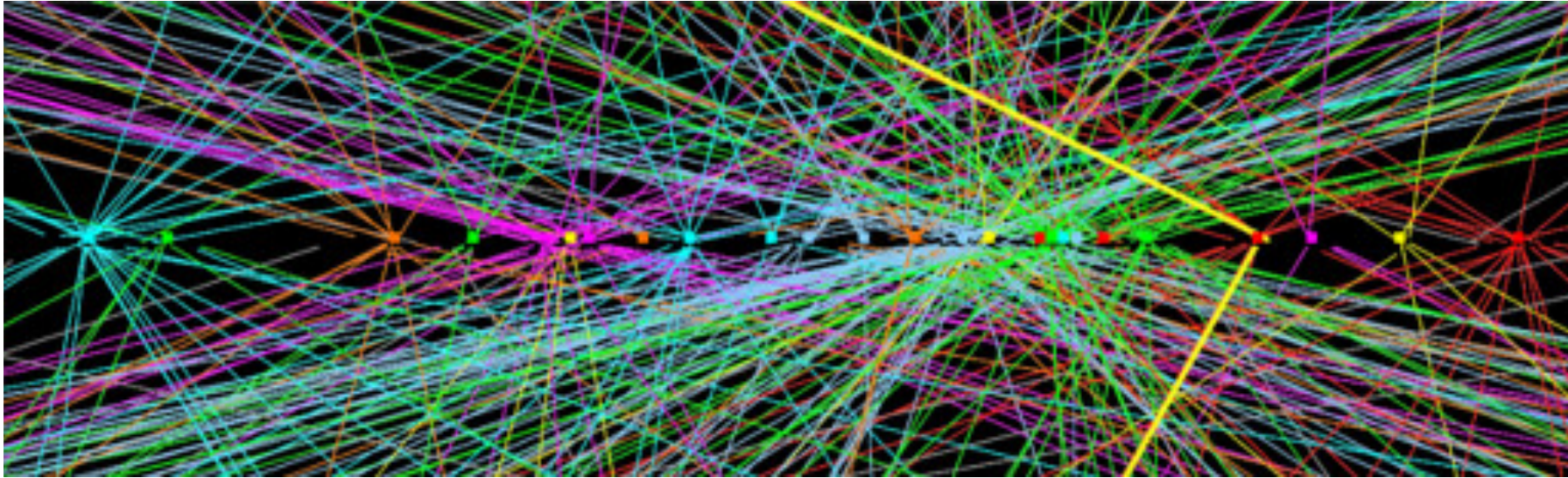
Lennart Huth

Silicon Detector Colloquium, DESY Hamburg, 21.11.2022
HELMHOLTZ



Why do we need silicon detectors?

Vertex and momentum reconstruction in particle physics experiments

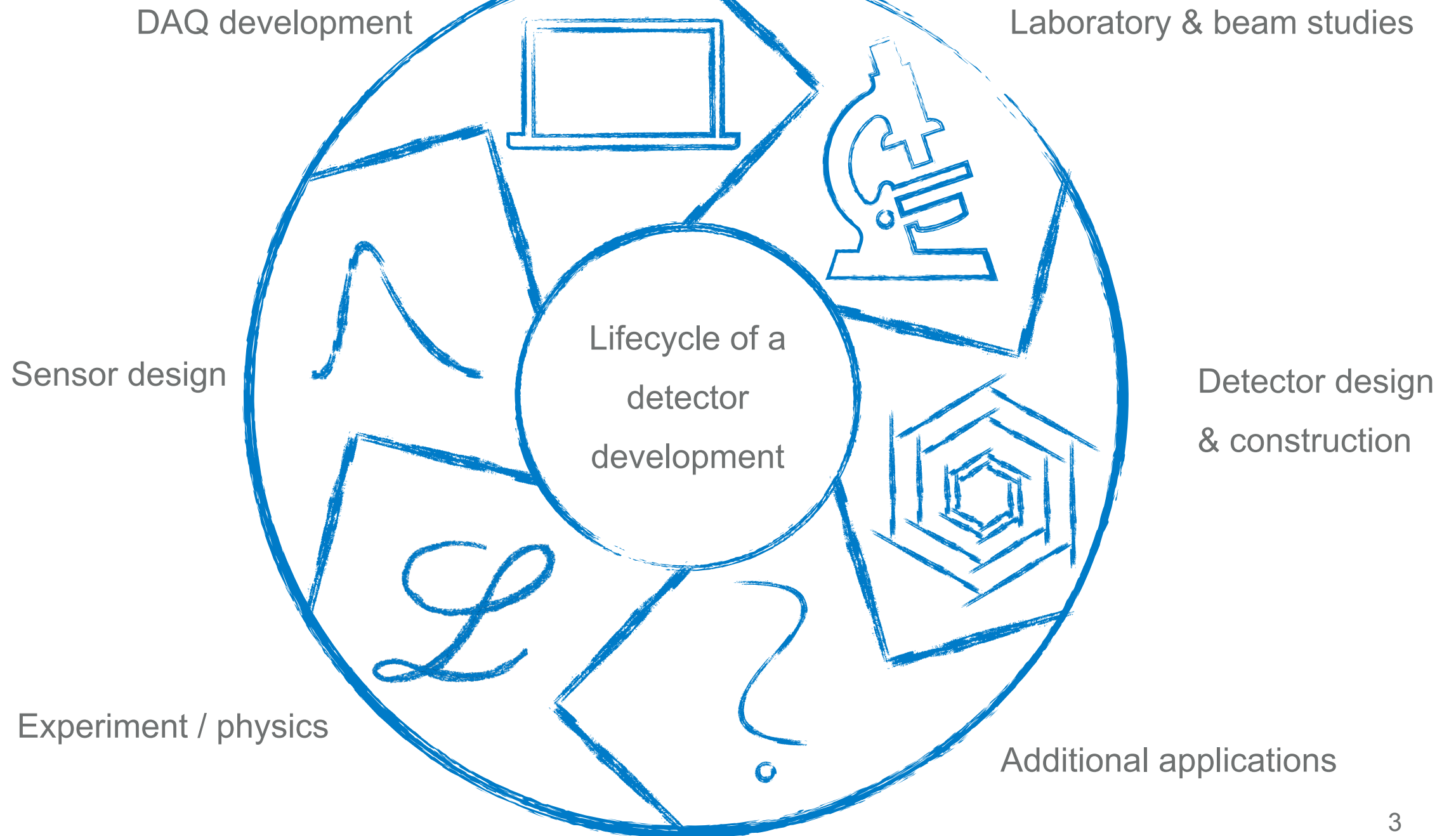


CMS

From collision to physics with silicon tracking detectors:

- Number of particles
- Vertex-position
- Momentum (in B-field)

	HL-LHC	Lepton collider
x/X_0	10 %	<1 %
Time resolution	25 ns	< ns
Pitch	50 μm	< 25 μm
Point resolution	15 μm	3 μm
$n_{\text{eq}} / \text{cm}^2$	10^{16}	10^{11}



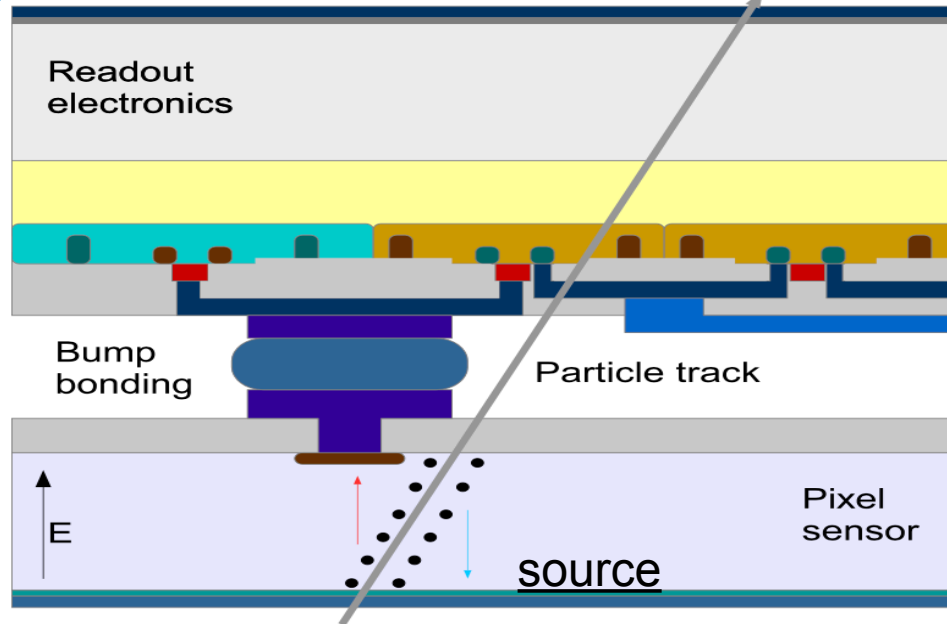
Sensor design

Choosing the right technology and design



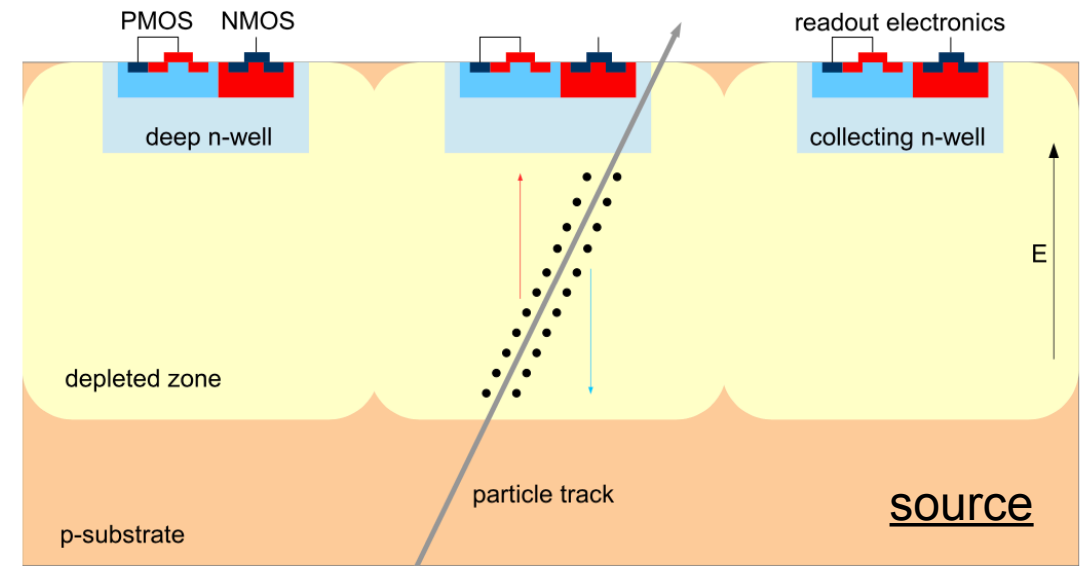


Hybrid vs Monolithic



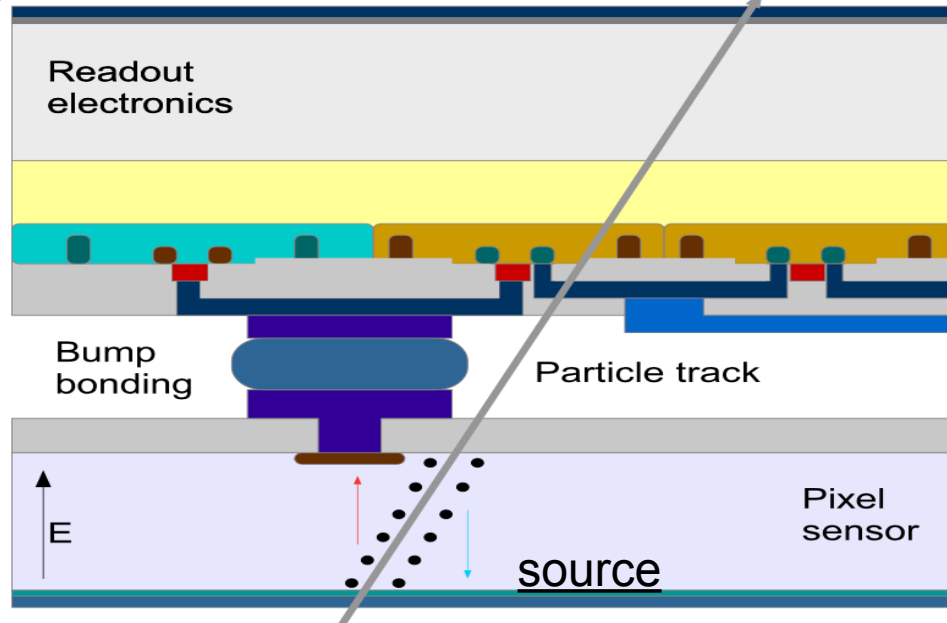
- Two silicon pieces: active sensor chip and readout
- 20 years+ in many vertex detectors
- Specialised process → expensive and limited vendors
- Bump bonds limit pixel pitch and material

- Readout and sensitive structures in one
- Industry process, largely available
→ Simpler, thinner and cheaper detectors
- Mostly 180 nm technologies in advanced sensors



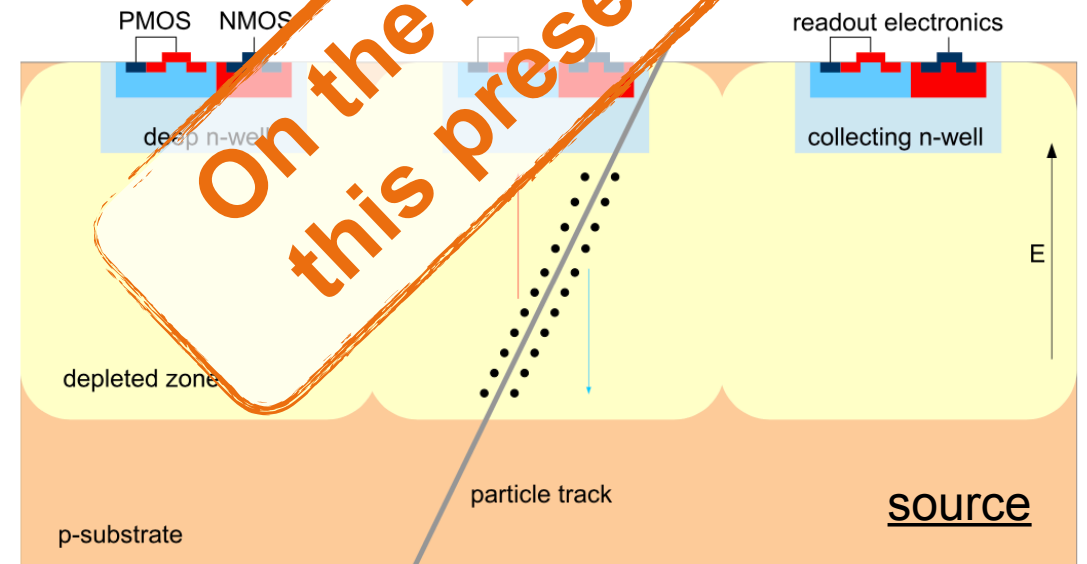


Hybrid vs Monolithic



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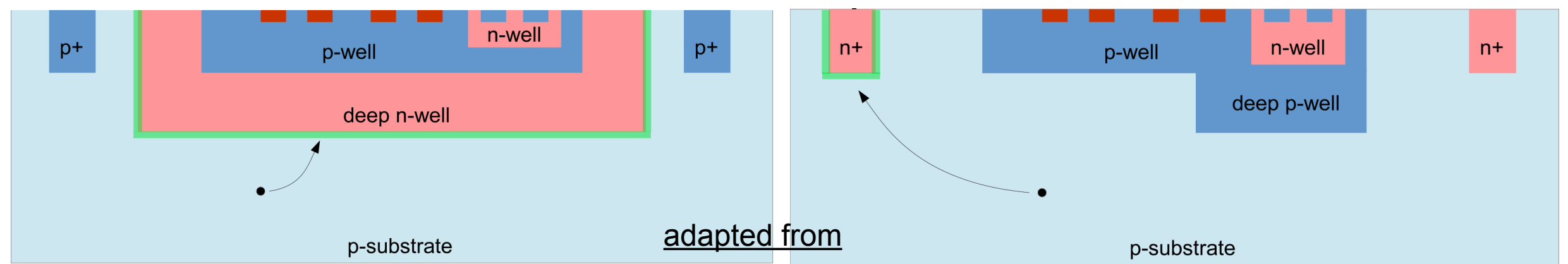
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Two approaches on MAPS

Large and small fill factor designs

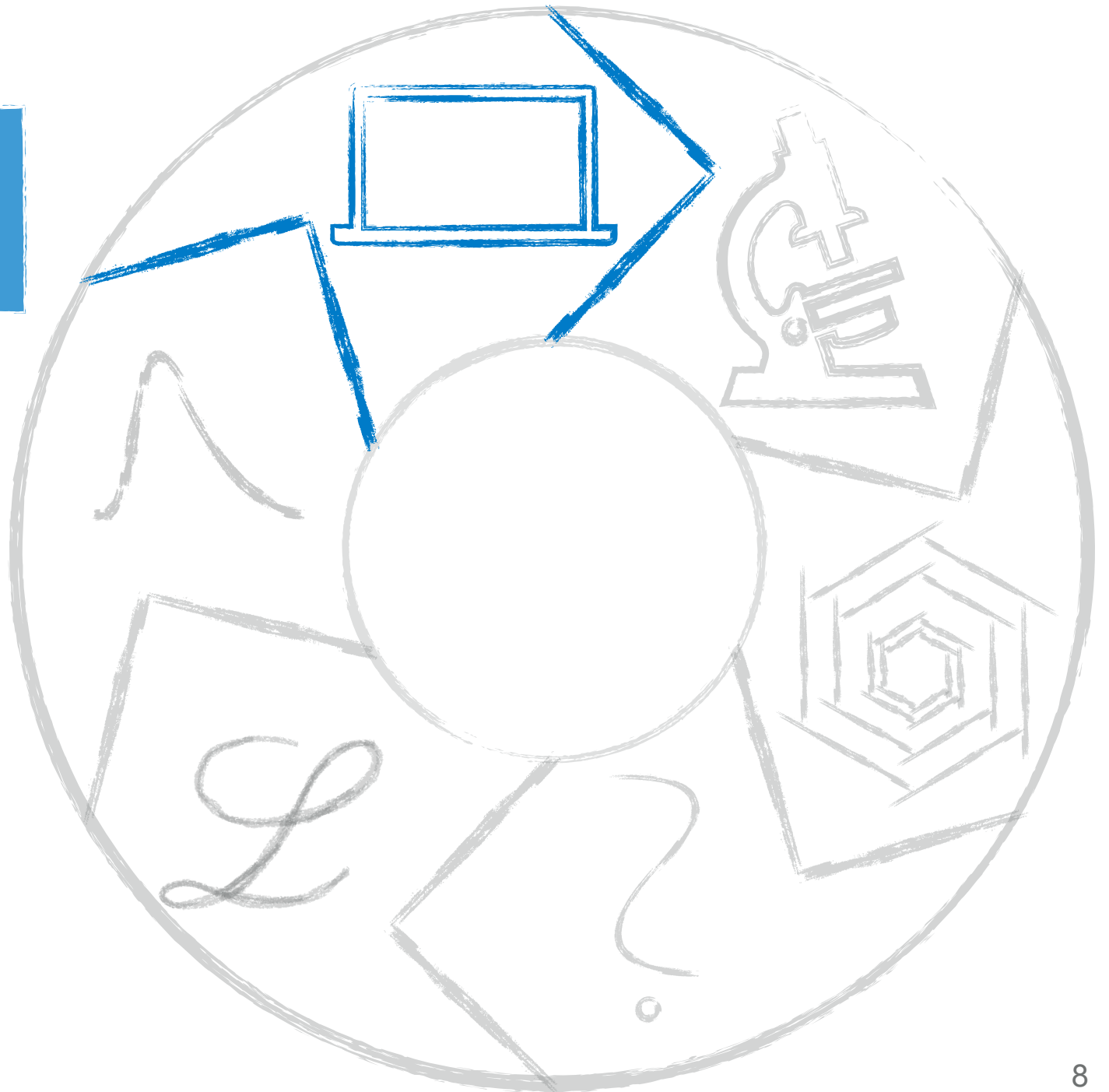


- Large fill factor
 - Large collection electrode
 - Higher noise
 - Fully depleted - high voltage
 - Short and constant drift paths
 - Example: HV-MAPS
- Small fill factor
 - Small collection electrode
 - Lower noise
 - $< 20 \mu\text{m}$ depleted high resistivity
 - Variable propagation length
 - Example: ALPIDE

Technology choice at the end application driven

Data acquisition systems

**Developing
readout for
testing and
experiments**



The MuPix Telescope - towards the Mu3e detector

A test beam DAQ for HV-MAPS tests

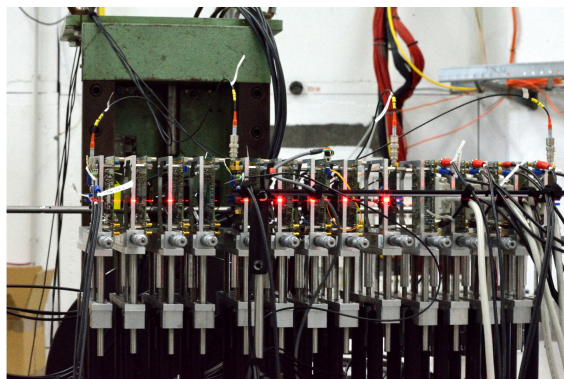
Single Chip DAQ

- PCB carrying Chip
- Connection to FPGA/PC
- DAQ soft- and firmware



MuPix8 Telescope - A slice of a vertex detector

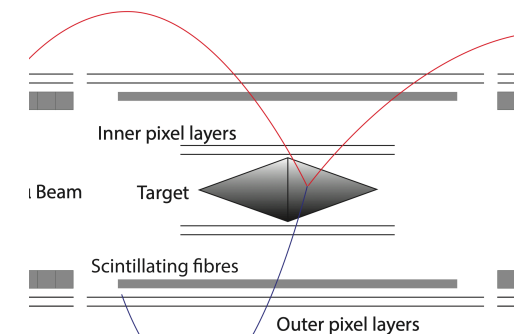
- Test of Mu3e DAQ concept: vertical slice including tiles
- Flexible workhorse deployed at DESY, CERN, PSI and MAMI from 2014 until today
- Up to 1.5 MHz particle rate



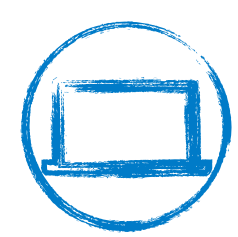
Mu3e Experiment

$\mu \rightarrow eee$ in SM only with $BR < 10^{-50}$

- Observation == new physics
- Muon decays at rest, thin tracker



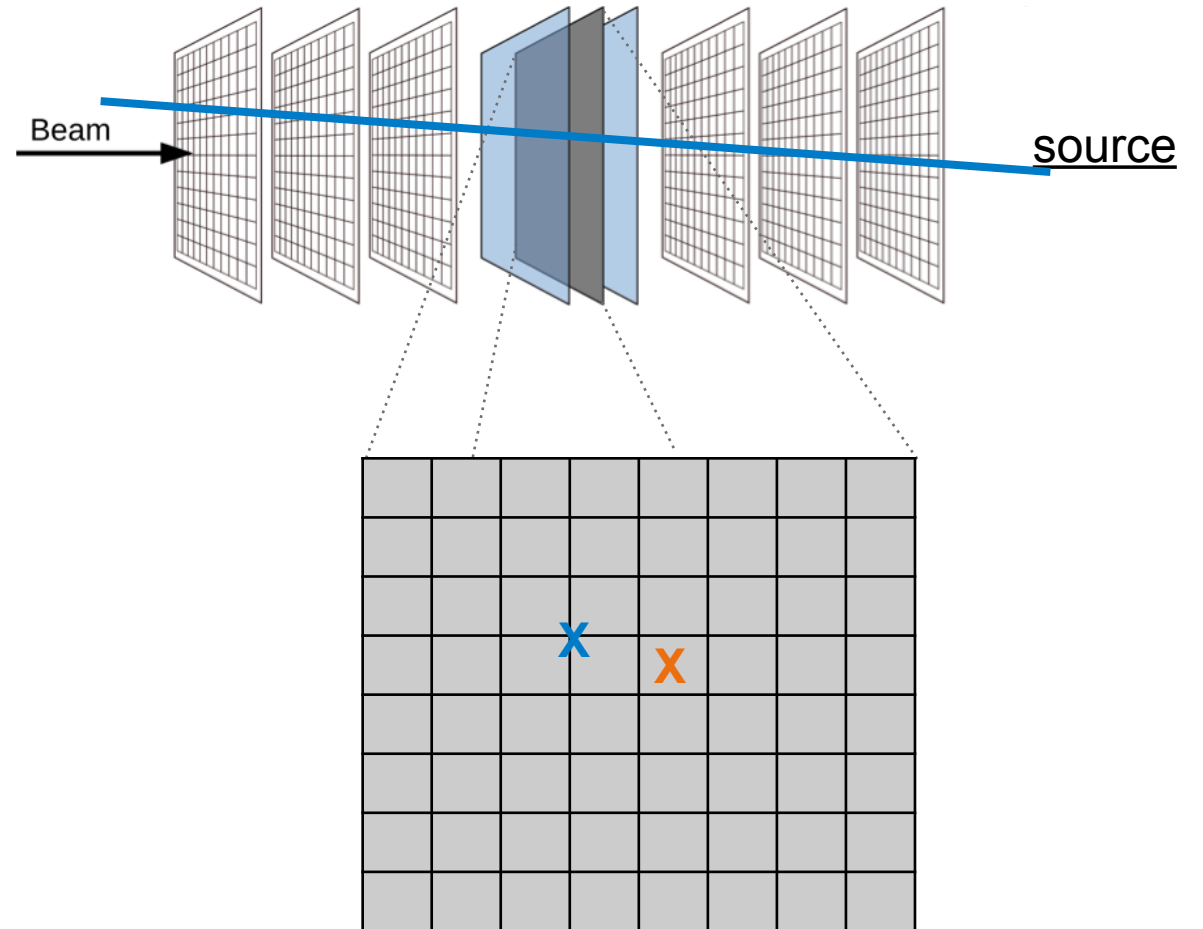
TDR

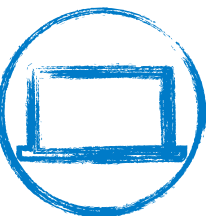


Particle tracking telescopes

From prototype to detector system

- Precise reference system for test beam studies
- Test bench for sensor integration tests
- At low momenta: As thin as possible to minimise trajectory disturbance
- 2 approaches presented
 - MuPix telescope: High rate capability/timing
 - EUDET telescope: Highest spatial resolution



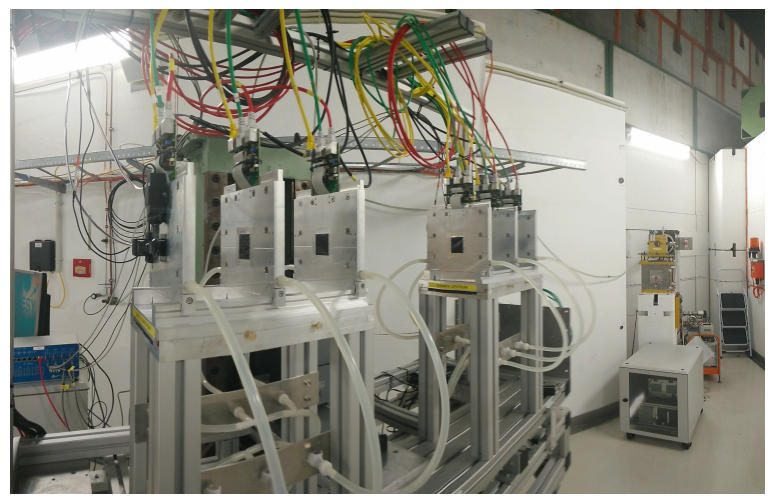


DESY II Test Beam

Providing beam and the ultimate toolkit for sensor studies

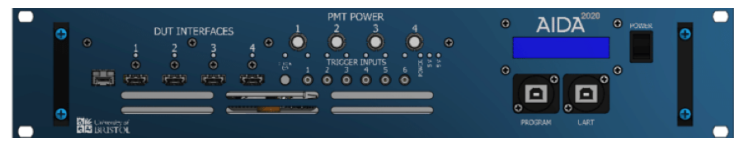
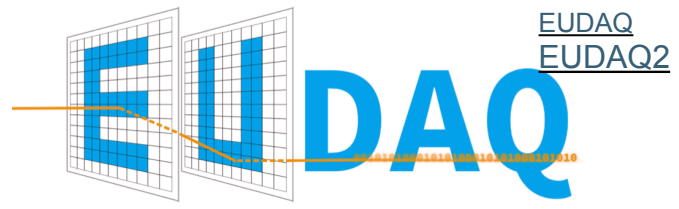


Reference Telescope



- 6 MIMOSA26 planes
- 3 μm resolution on DUT
- 115-230 μs integration time
- Installed at DESY, SPS, ELSA and SLAC/TRIUMF

Common DAQ

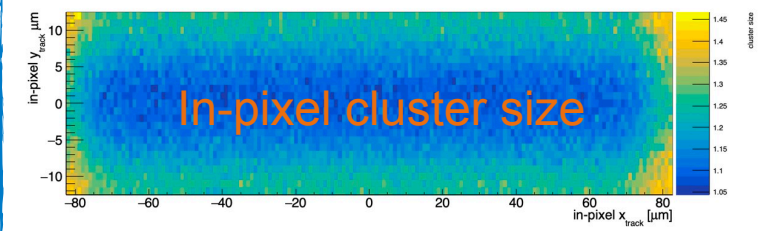


Identical setups at different beam lines

- EUDAQ: Distributed DAQ framework
- AIDA-TLU: Flexible DUT integration
- Active developments in AIDA: Task 3.4 - Next gen DAQ



Analysis Framework

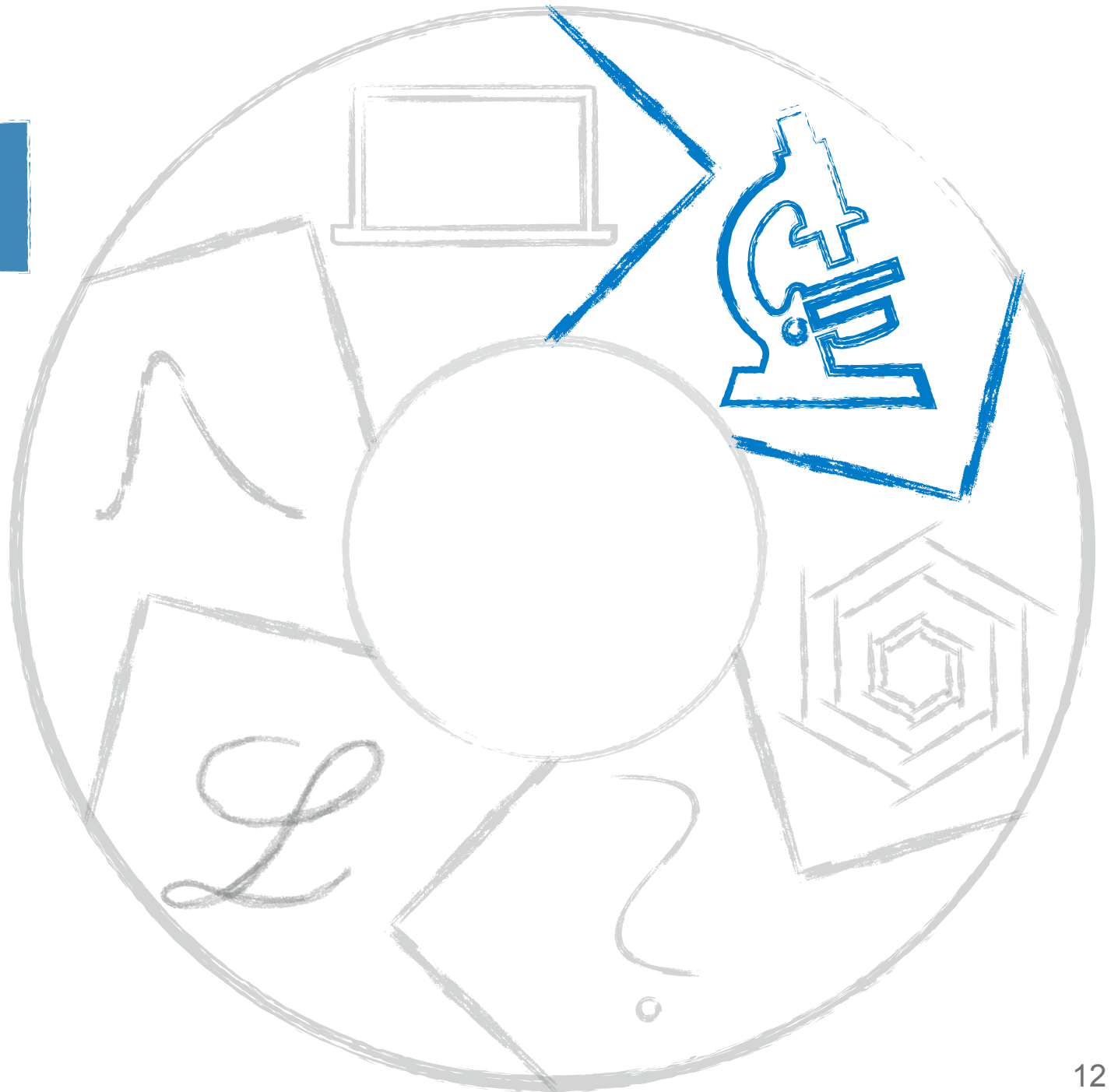


Modular framework

- Flexible event building
- Clustering, track reconstruction (Line or GBL), alignment and analysis modules provided
- Active community \rightarrow continuous improvements
- Well documented \rightarrow low starting threshold

Characterisation

Understanding and
optimising everything

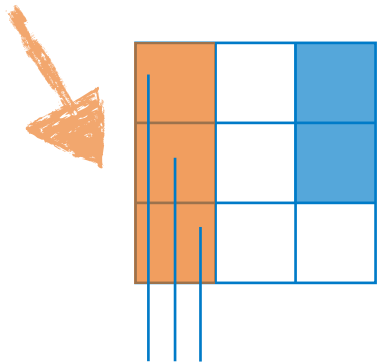


Example: Clusters and crosstalk on readout lines



Assumption:

- Clusters at the test beam with perpendicular impact can be maximal 2x2
- Expect to see only few/none with 3 pixels along x/y

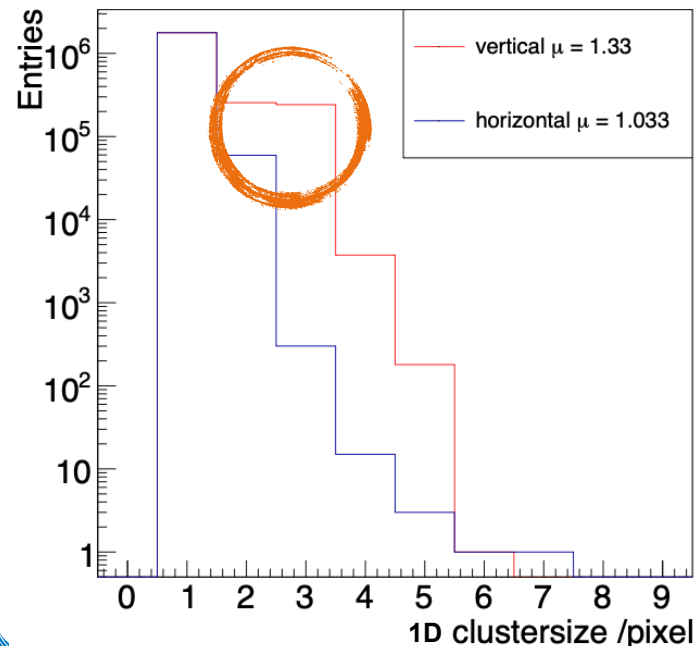


PhD thesis

MuPix8:

- First 2 cm high HV-MAPS
→ long connection lines from pixel to digital cells

Observation

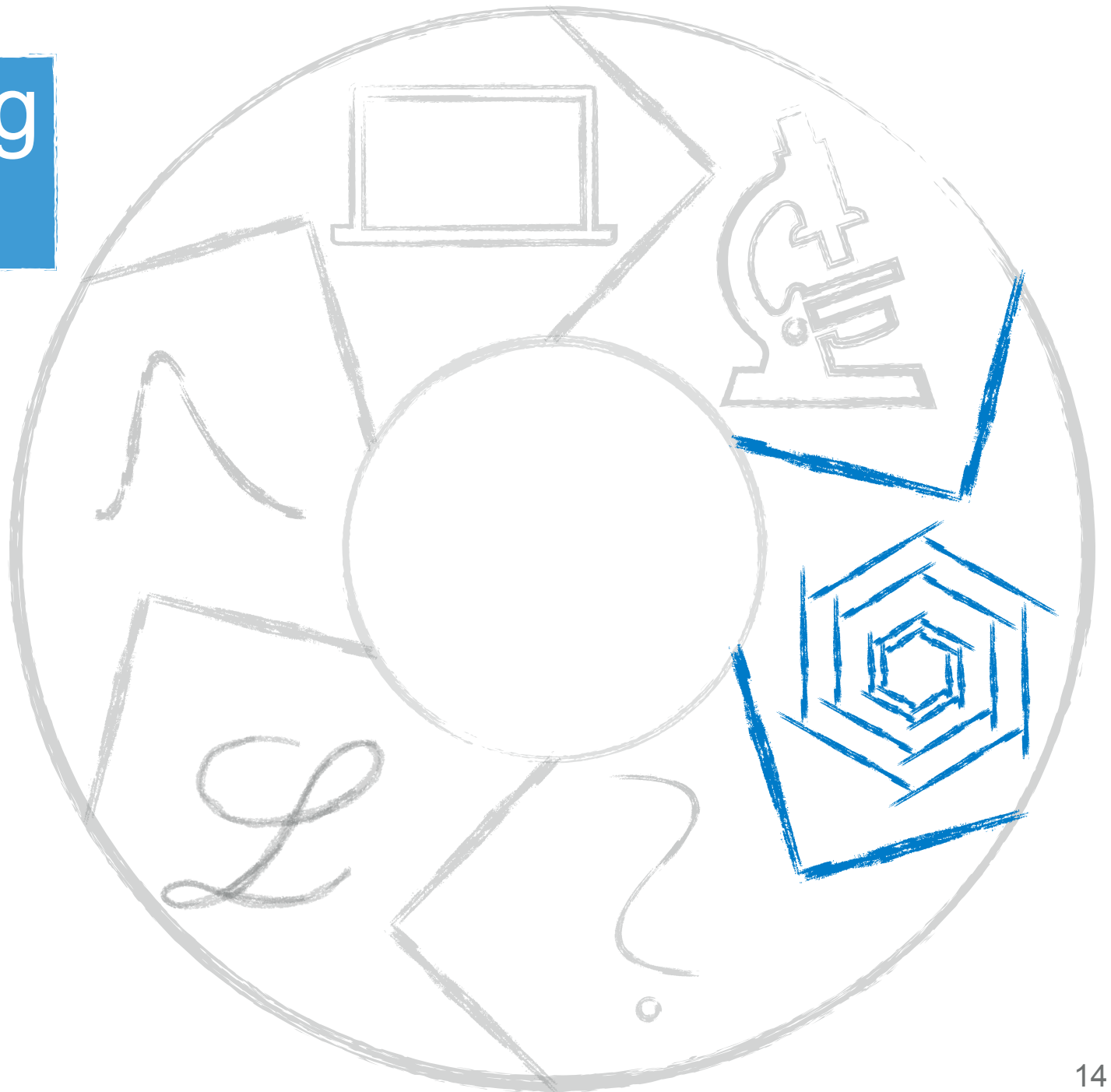


Conclusion

- Connection lines introduce crosstalk
- longer lines → larger crosstalk
- Issue solved for final chip by improved routing scheme

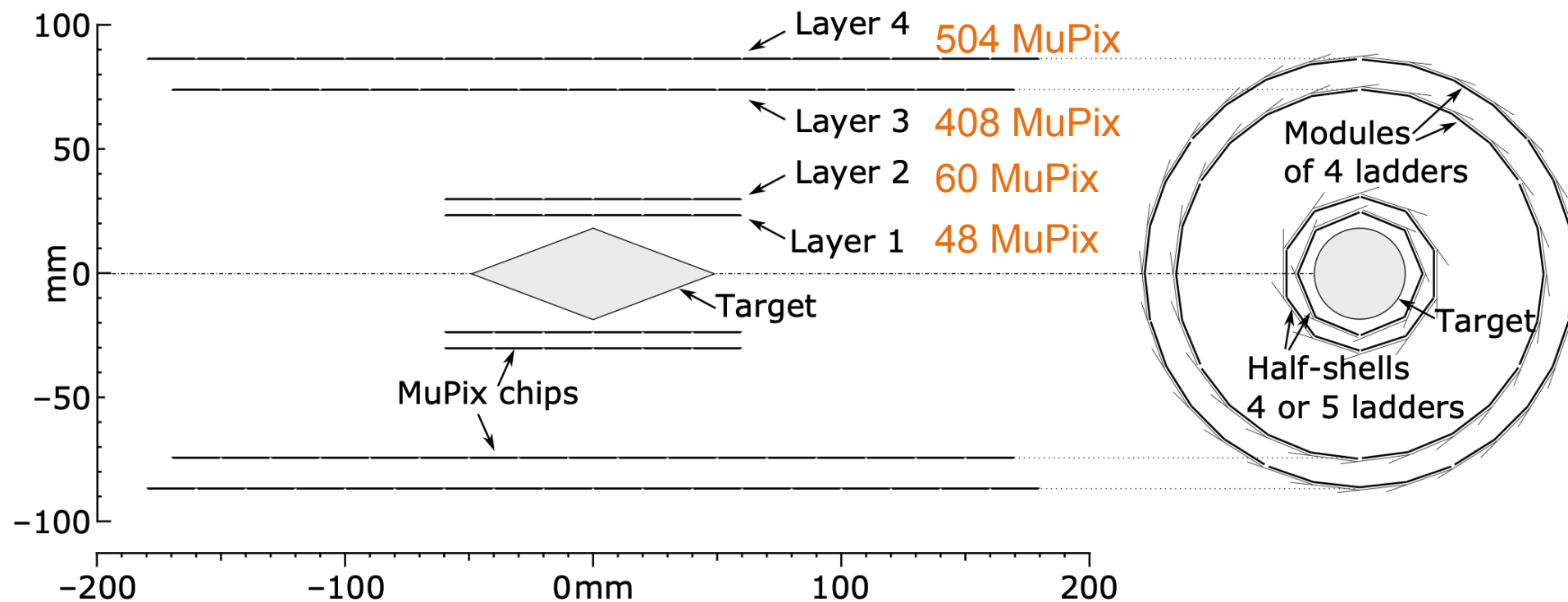
Designing/building a detector

**The transition
from a sensor to
an experiment**



The Mu3e tracker

An extremely low material tracking system



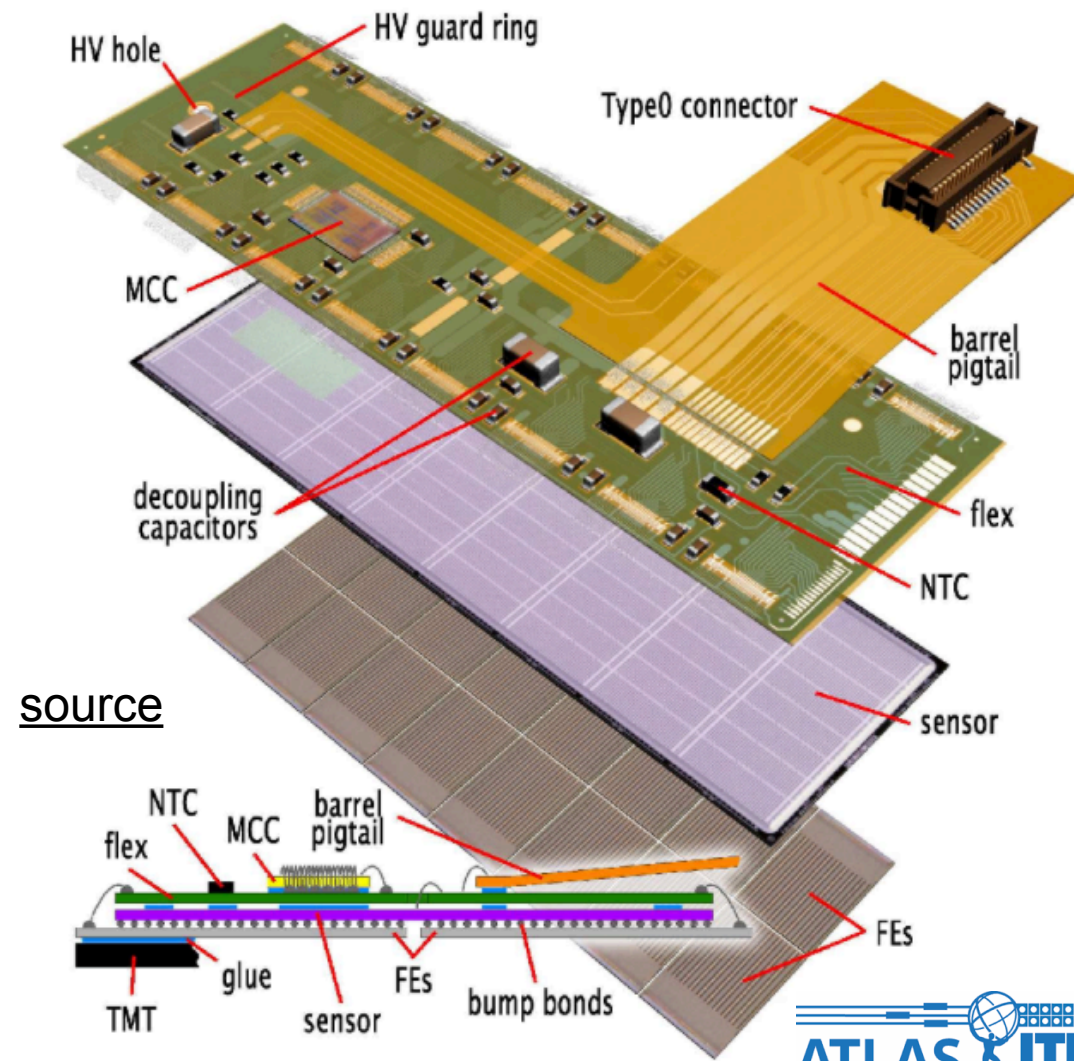
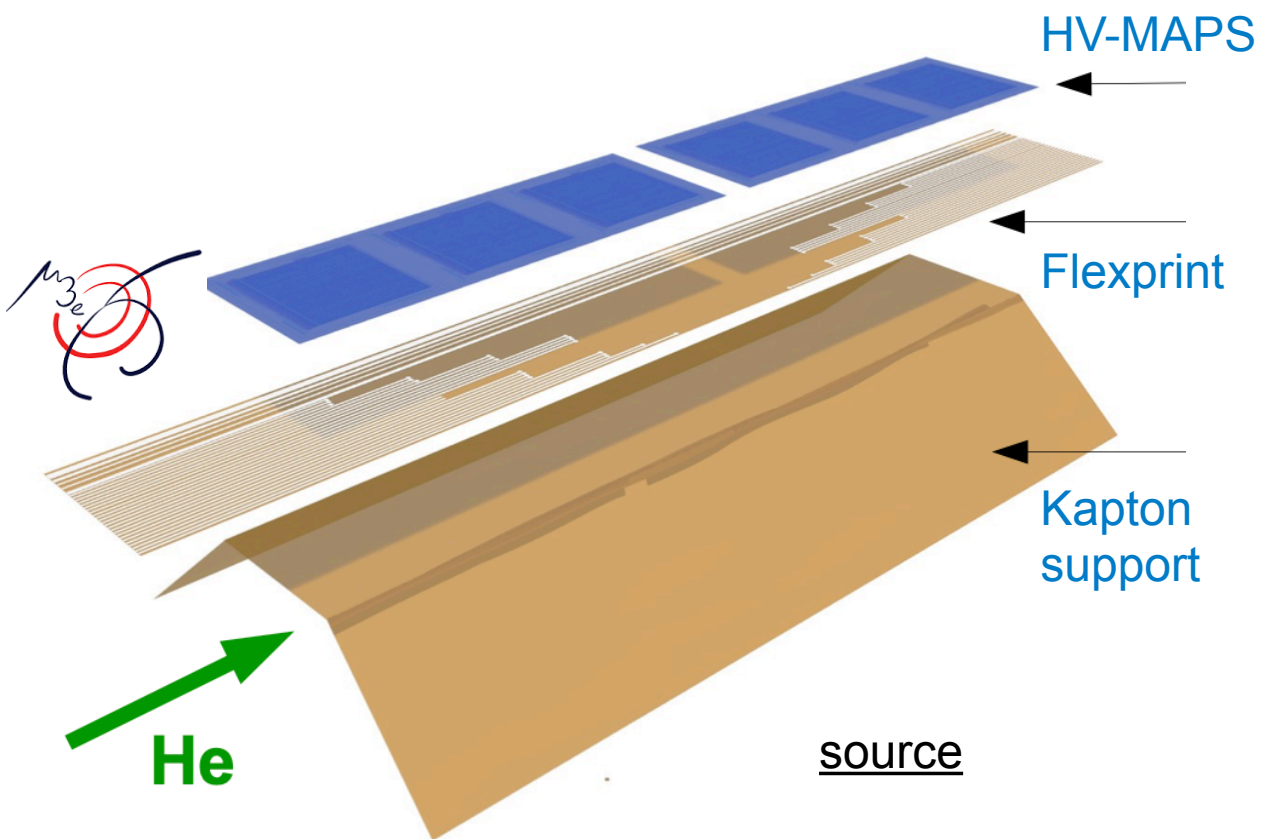
1128 fully functional MuPix chips on 70 modules

@ $< 0.1\%$ x/X_0 per module layer



The beauty of simplicity

Simplified detector construction with highly integrated sensors





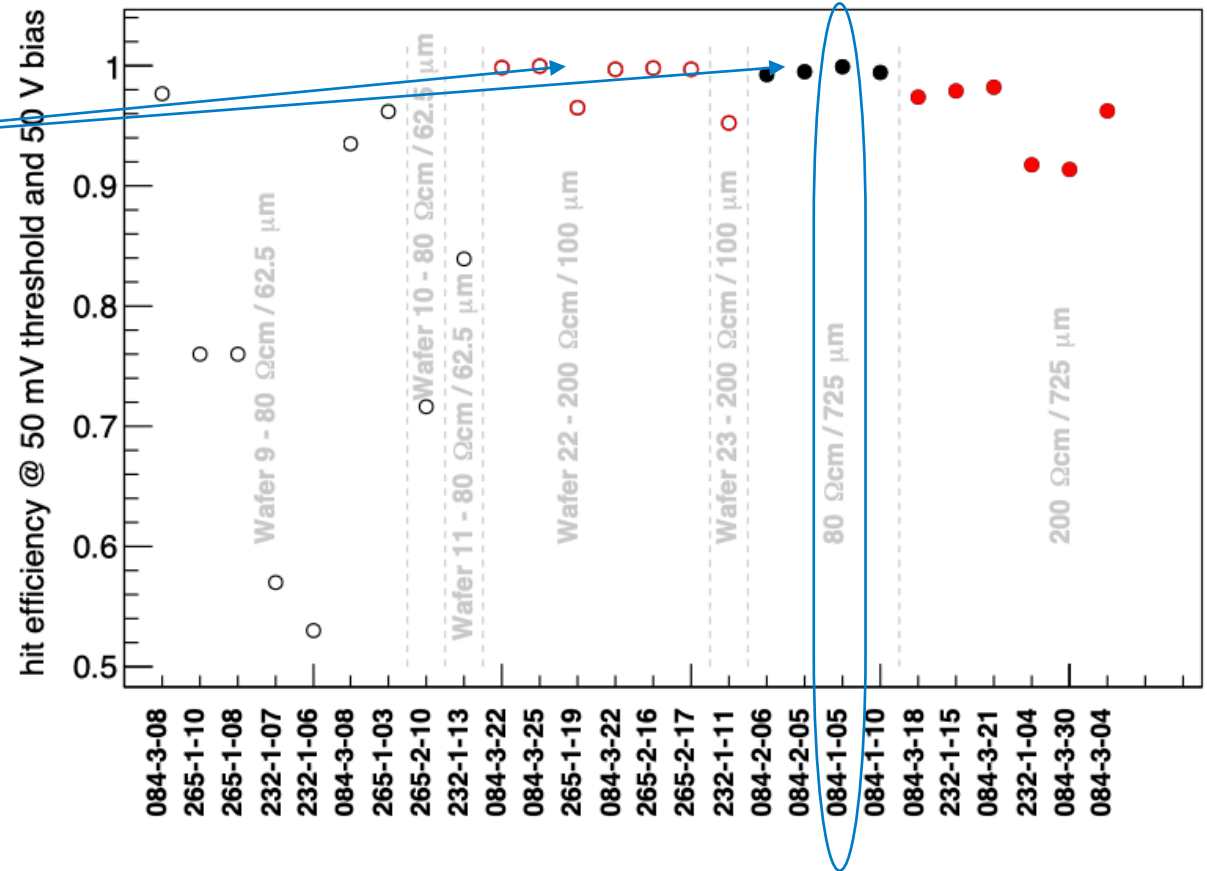
Moving from single sensors to a production

PhD thesis

Understanding performance fluctuations

Tested sensors from 7 wafers

- Only 2 with good yield
- Others show varying sensor performance
- Traced down to dicing/thinning process
- Company fixed issue
- Wafer probing for final production



Back to the future - Generic R&D at DESY and its future



Many ideas but **no**
experiment proposal at DESY

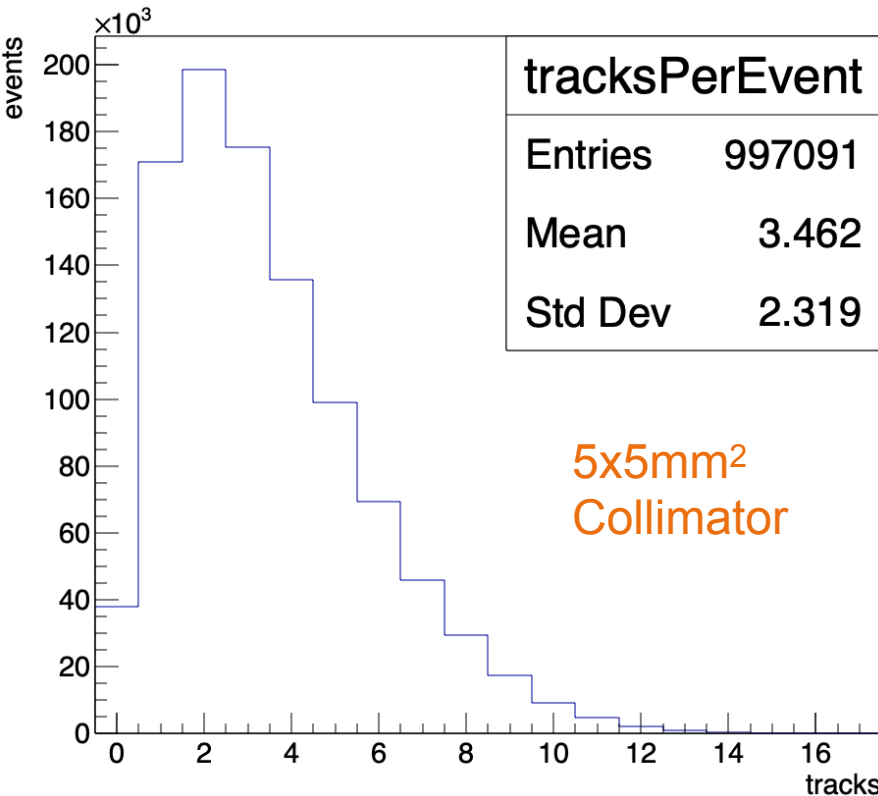
Generic Sensor R&D /
Infrastructure Improvements

Potential Applications

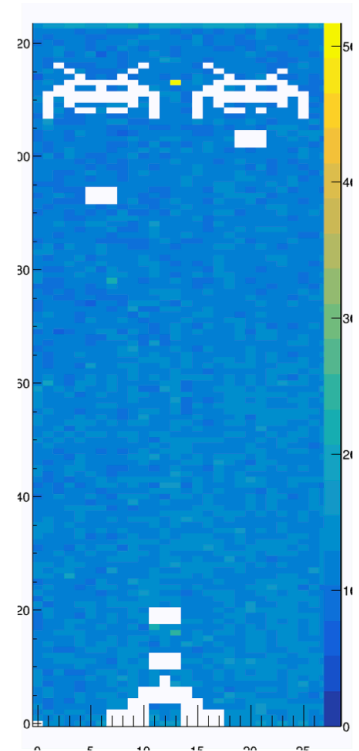


Improving the time resolution of the beam telescopes

TelePix: An HV-MAPS as a trigger and timing plane



- HV-MAPS as trigger and timing layer
- PI of QU-funded project (ca 80k EUR invest)
- Trigger on OR of all unmasked pixels
- Full EUDAQ2 + AIDA TLU support



Pixel masking

CLUSTER OF EXCELLENCE
QUANTUM UNIVERSE



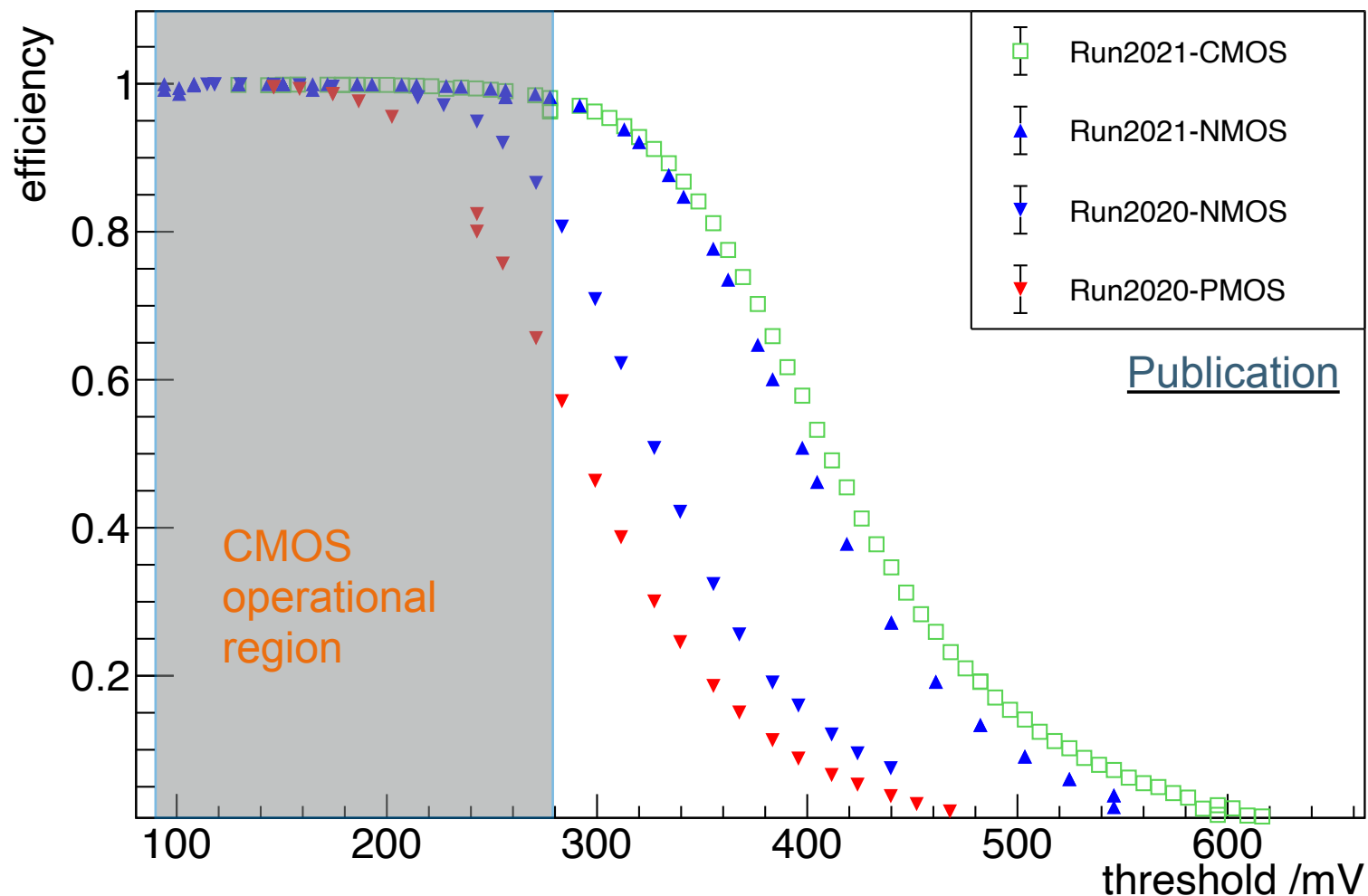
UNIVERSITÄT
HEIDELBERG
ZUKUNFT
SEIT 1386





Improving the time resolution of the beam telescopes

Performance results: Efficiency



Publication

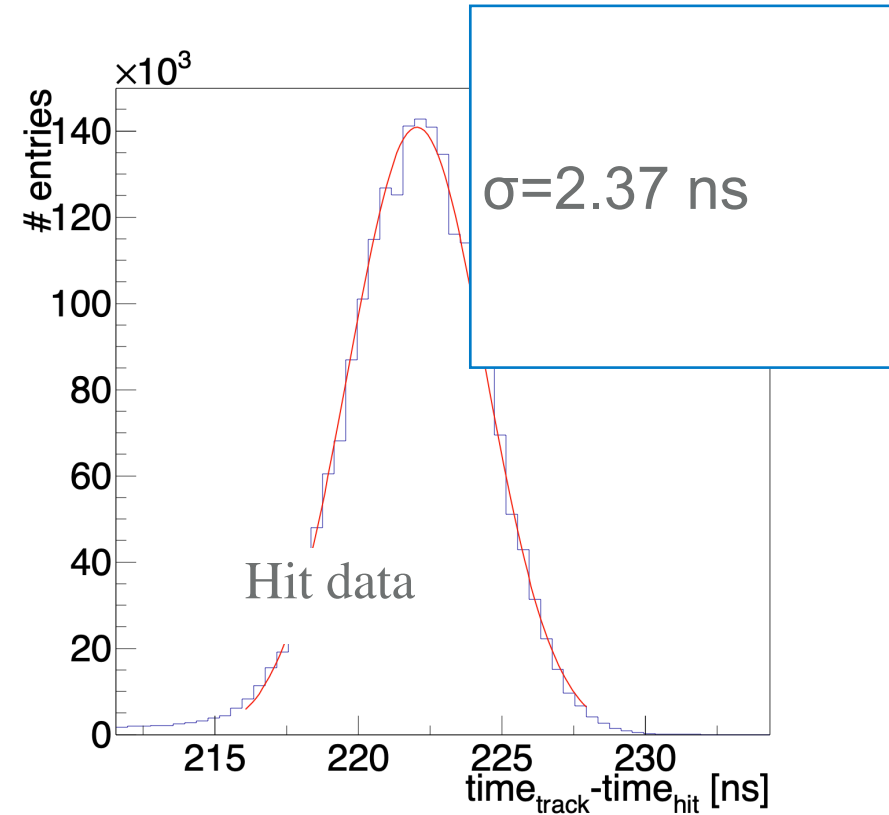
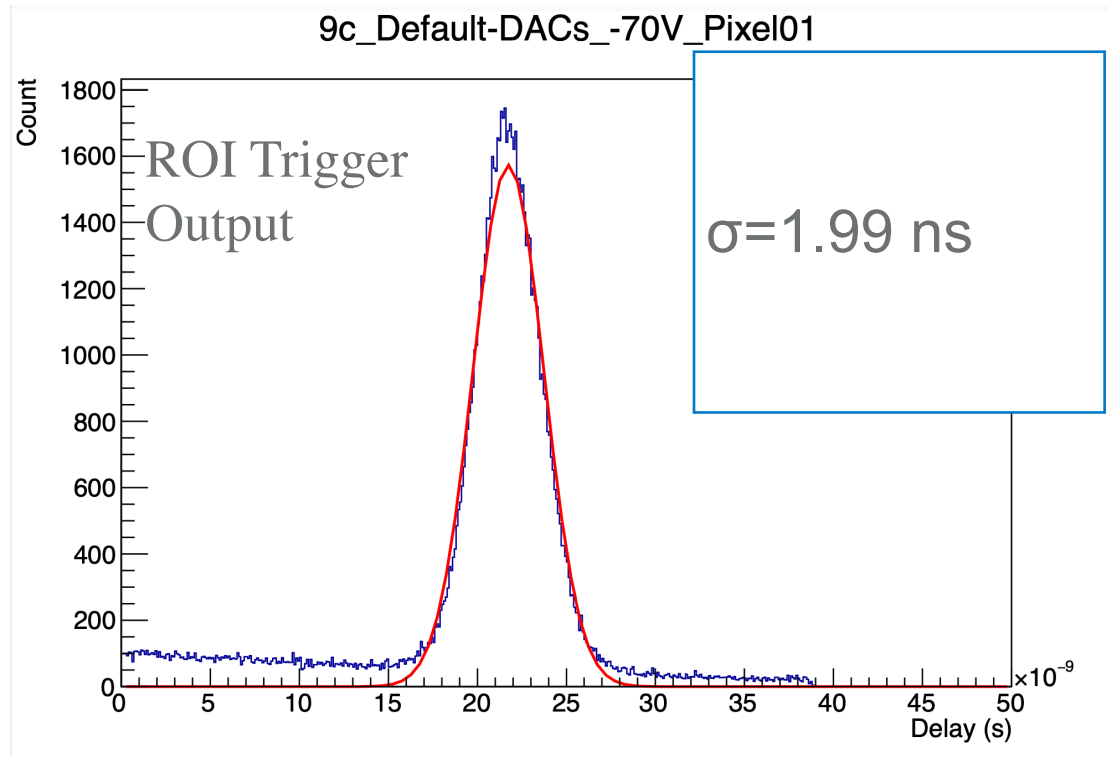
- Studied 4 amplifier flavours
- Run2021 outperforms Run2020
 - Improved biasing
- CMOS version optimal: ~200 mV operational region
- Noise 0.01 Hz/pixel ($2.5e^{-10}/\text{BC}$)



Improving the time resolution of the beam telescopes

Performance results: ROI trigger and timing

Preprint submitted to NIM-A



ROI trigger and data stream show excellent time resolutions

→ Full scale sensor expected back December, to be put in operation in **2023**



A detailed illustration of a cross-section of an orange. The orange is cut horizontally, revealing its internal structure. The outer rind is a thick, textured layer of orange-brown color. Inside the rind is a layer of lighter orange, fibrous material. The core of the orange is composed of several segments, each with a distinct, lighter orange, fibrous texture. The segments are arranged in a circular pattern around a central, star-shaped core. The overall appearance is that of a fresh, ripe orange.

-
- A large, curved, multi-colored solar panel array, likely a thin-film solar cell, showing a grid pattern of small cells and a prominent rainbow-like reflection.

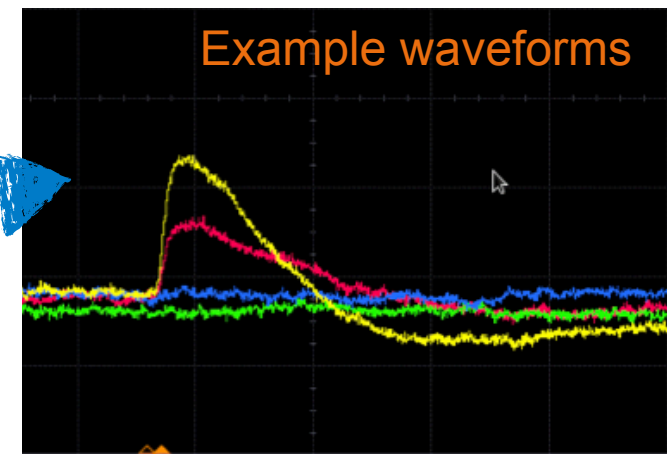




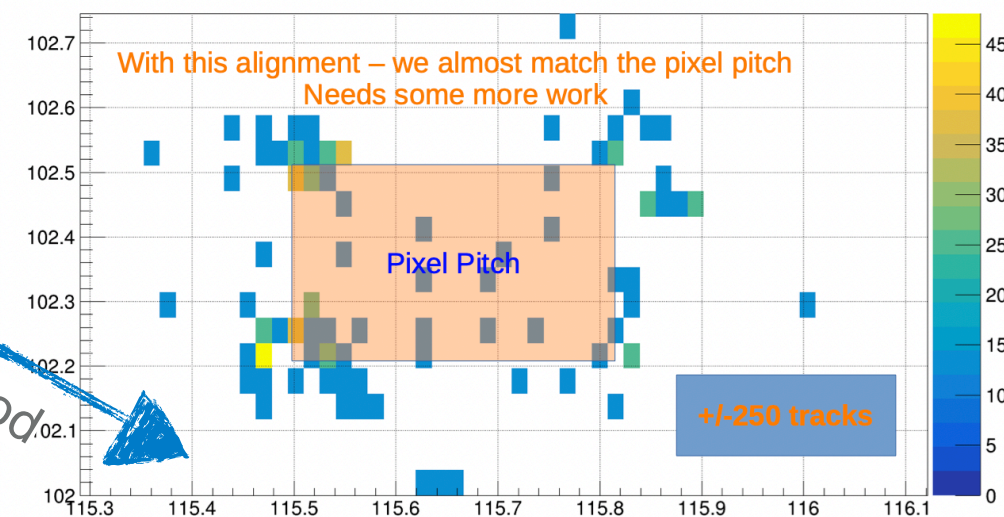
DESY CSA chip

- 4 analog channels with charge sensitive amplifier & Krummenacher Feedback
 - 16.3 μm pitch low event rates
 - Efficient only underneath electrode
- Miscommunication during design phase

Circuit functional



Understood



Track positions with signal on MLR1

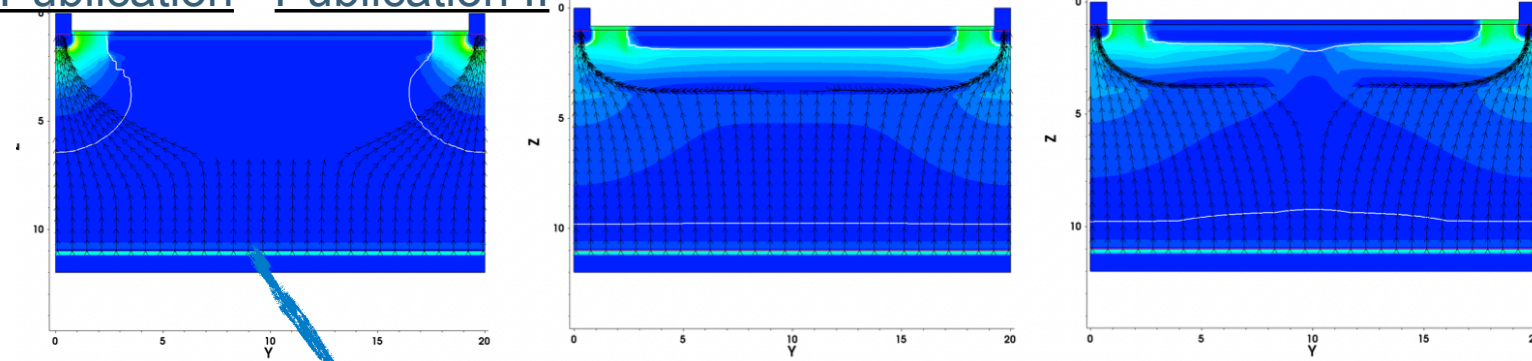




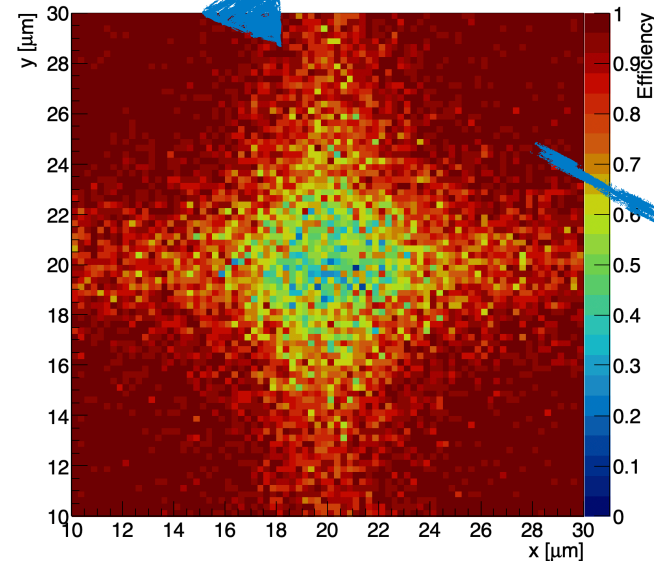
Analog pixel test structures (APTS)

TCAD - Finite Elements simulation

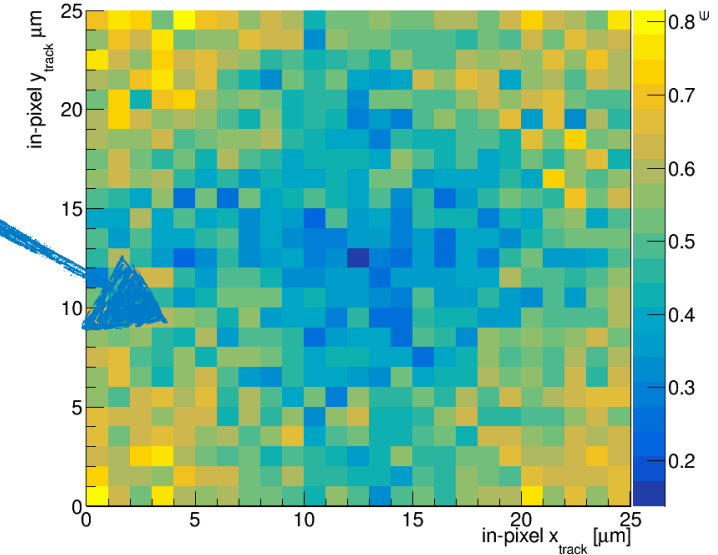
Publication Publication II



- Three design flavours with different field configurations
 - Studied in TCAD, Monte Carlo, laboratory and test beam
 - Consistent results for all three
- Verified simulations can be used to engineer sensor layout and performance
- Continue the Tangerine efforts beyond 2023



Allpix² - Monte Carlo



DESY II Test Beam
TelePix as ROI trigger

Potential 65 nm applications

Medical applications:

- Monitoring of ion beams (HIT,...) for cancer therapy → in-situ treatment monitoring

Particle physics:

- LHCb is seeking for a monolithic upgrade of the outer tracker
- Belle II is looking for an upgrade
- Local experiments - e.g. LUXE
- New telescope
- **Higgs factory**

Technology transfer:

- 65 nm for **Petra IV/FLASH**
 - Stitching → large surfaces
 - On-chip intelligence
 - reduce data
 - Modern process
 - sustainable
 - Beam diagnostics (bunch population,...)
- Radiation detection
- Geology → cosmic tracking in deep underground caverns
- Particle detectors for schools/education

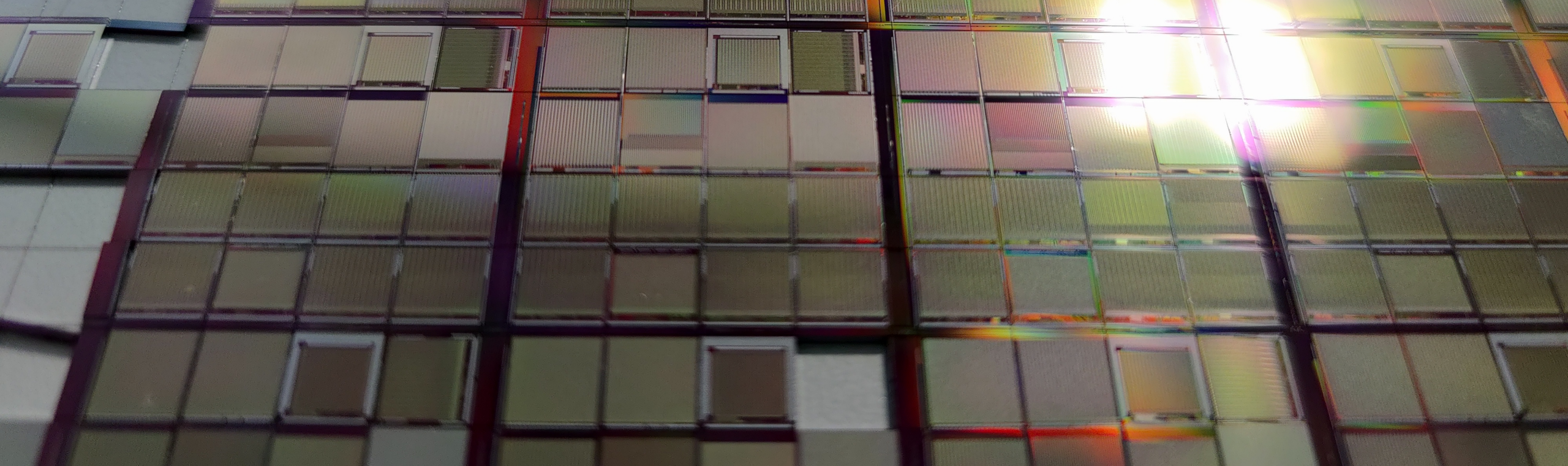


Summary

- DESY provides essential common infrastructure/software
- MAPS have shown their potential, that now has to be fully explored
- 65nm MAPS are future-proof → DESY could become leading institute for future vertex detector developments

**Exciting times are ahead for
silicon detector R&D**





Contact

Deutsches Elektronen-
Synchrotron DESY

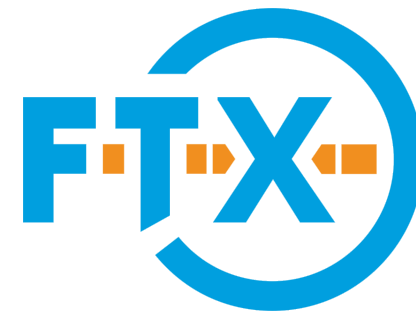
www.desy.de

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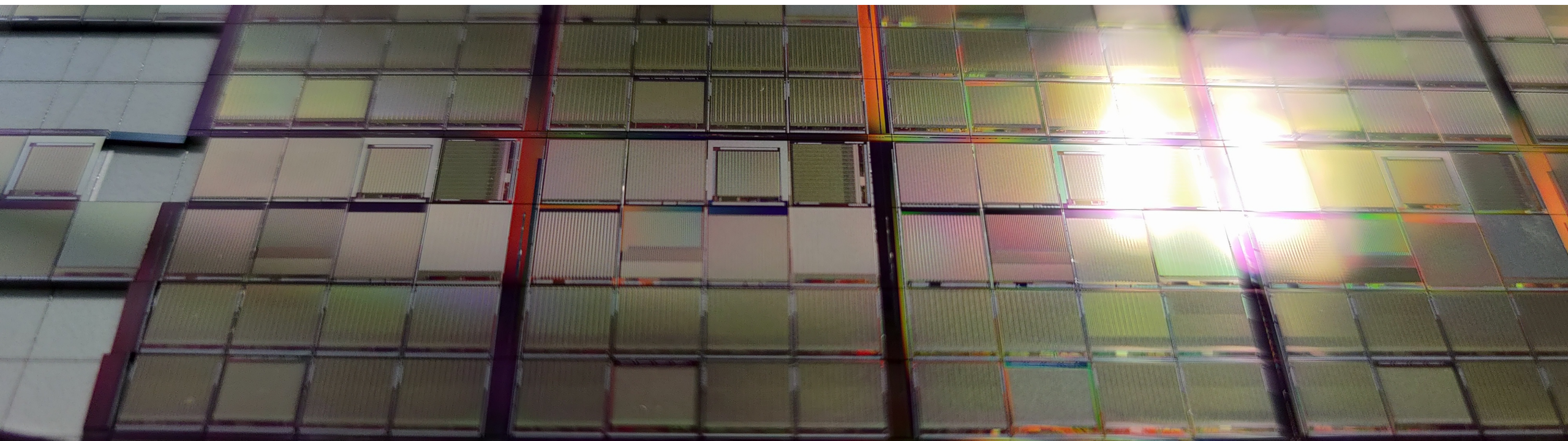
lennart.huth@desy.de

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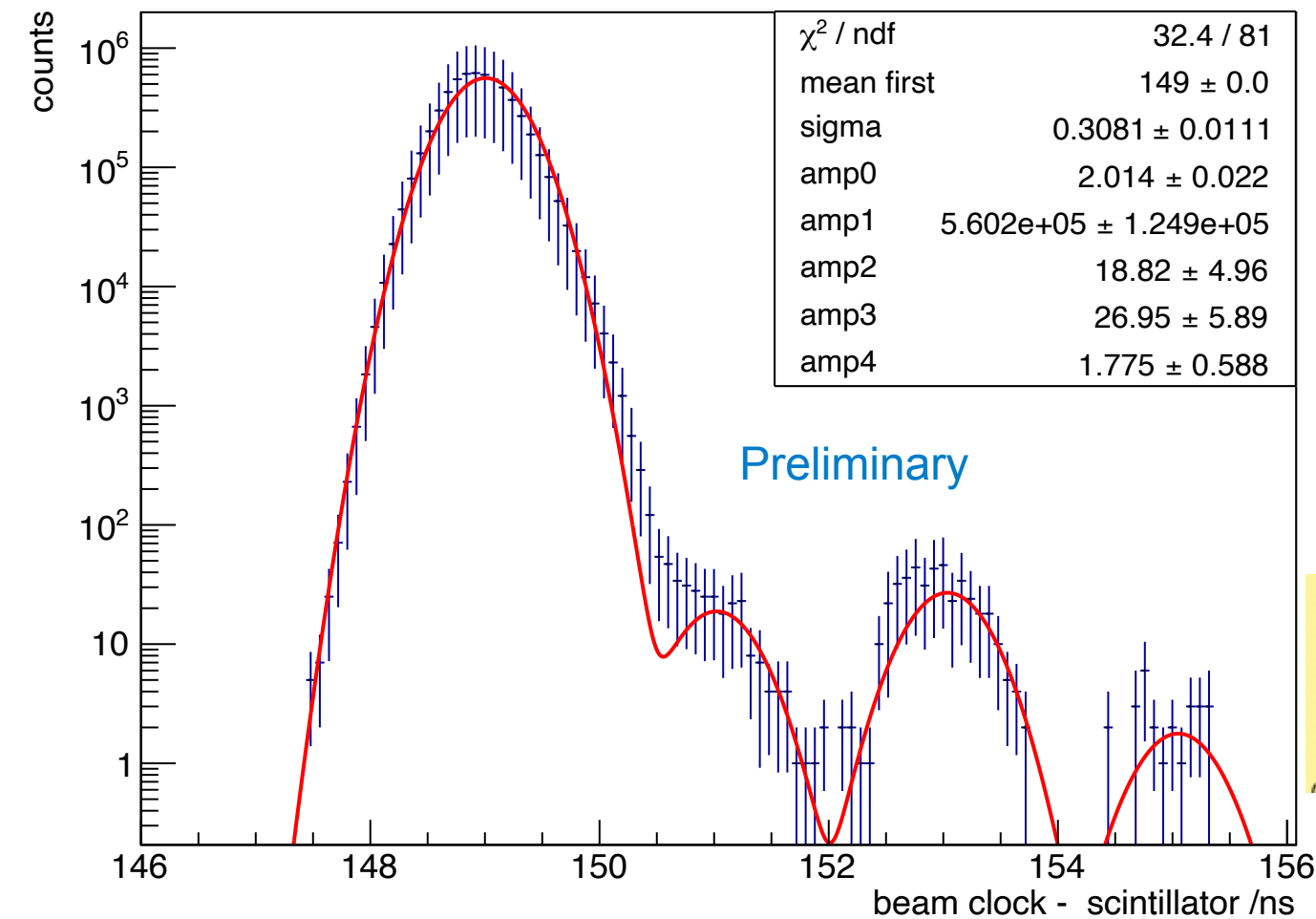


Backup



Measuring bunch structure with a fast timing layer

LYSO crystal to trigger the LGAD readout used to study the bunch clock - beam timing



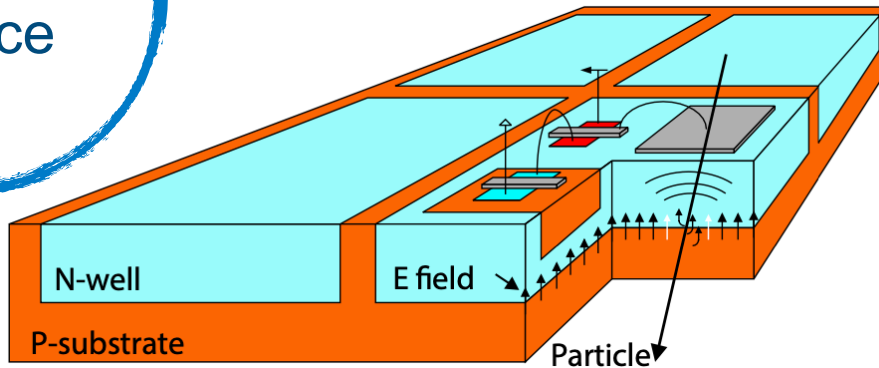
Probabilities

Hauptbunch: 99.9915%
1. Nebenbunch: $3.35\text{e}-5$
2. Nebenbunch: $4.81\text{e}-5$
3. Nebenbunch: $3.17\text{e}-6$

All Nebenbunche equidistant and equal width in fit. Bunchspacing **2.01ns**

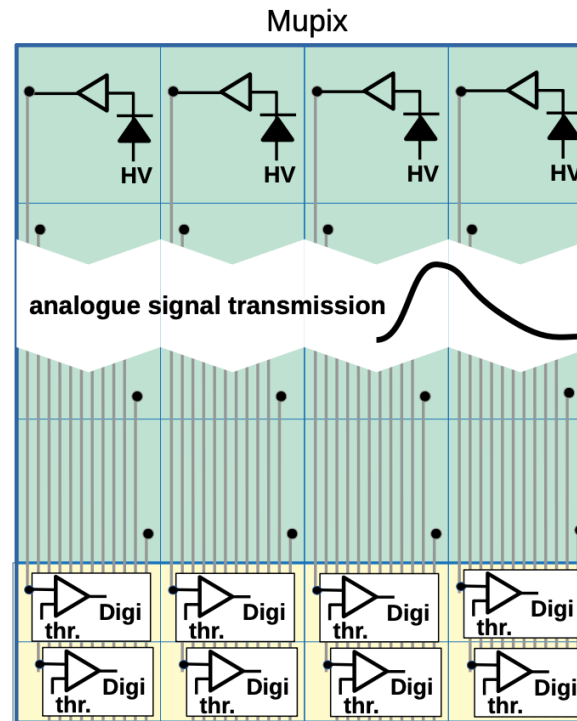
1	mean first	1.49007e+02	3.14367e-02	-3.45151e-06	-1.47339e-03
2	sigma	3.08078e-01	1.10621e-02	1.73421e-06	-1.38808e-02
3	amp0	2.01443e+00	2.15818e-02	8.79099e-06	-2.20820e-03
4	amp1	5.60245e+05	1.24854e+05	-3.85852e+01	-1.29486e-09
5	amp2	1.88201e+01	4.95867e+00	-2.08059e-04	2.84947e-06
6	amp3	2.69452e+01	5.89412e+00	-1.55420e-03	-7.95977e-06
7	amp4	1.77495e+00	5.87509e-01	2.96536e-04	-5.02792e-05

Technology
choice



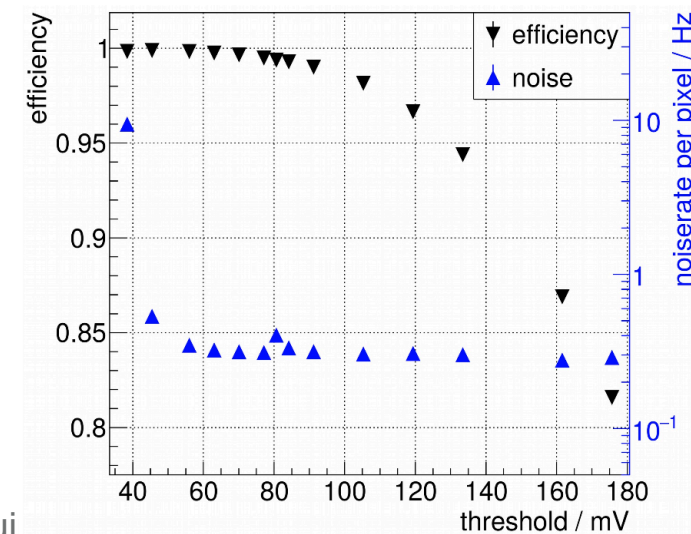
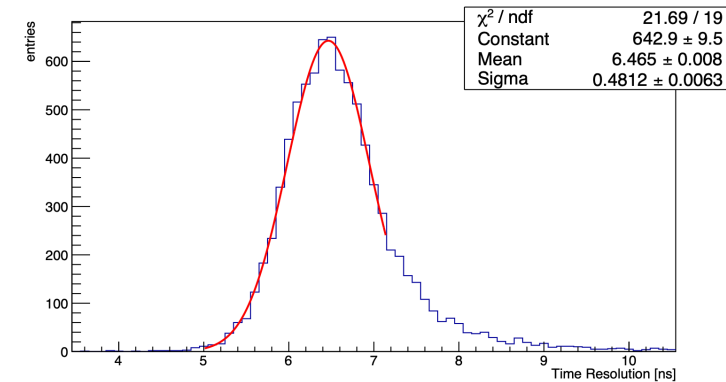
High Voltage Monolithic Active Pixel Sensors (HV-MAPS)

- 255x255 pixels, 80 μm pitch
- In pixel amplifier and line driver
- Point-to-point connection to periphery
- Digitisation, threshold trimming, time stamping
- Zero suppressed data driven readout @ 1.25Gbit/s LVDS

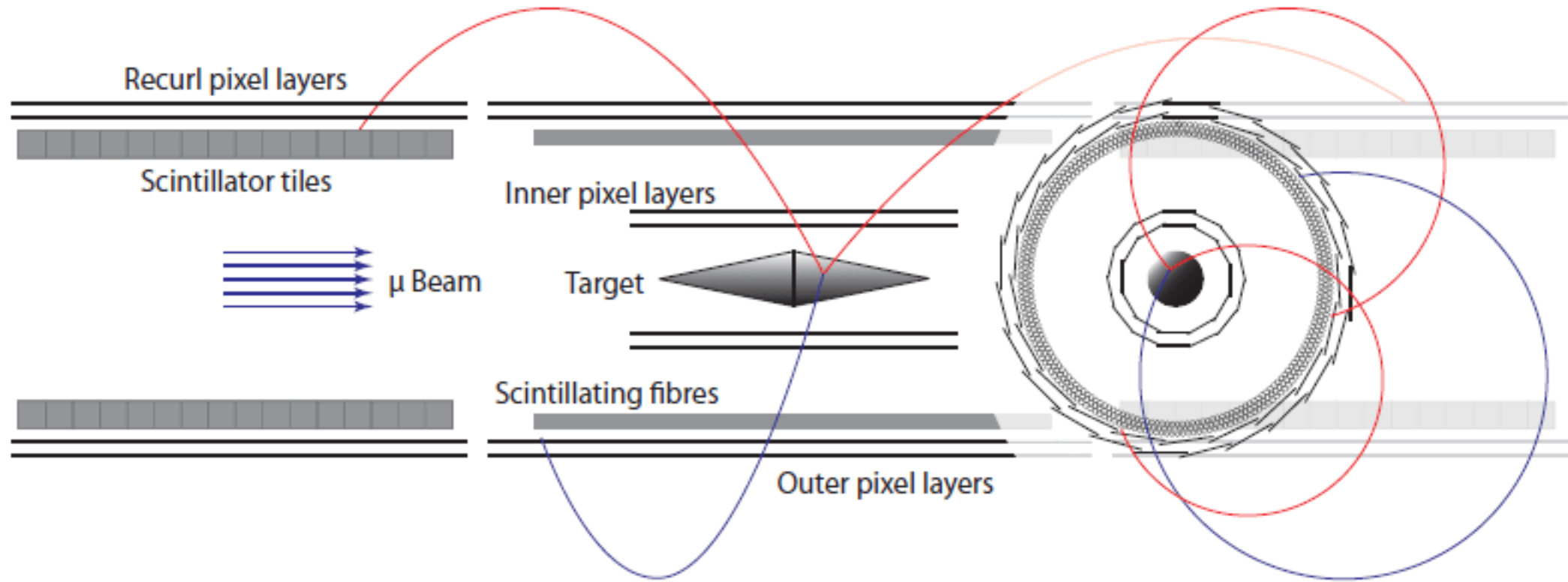


Large Scale HV-MAPS MuPix8
fulfilled all specifications:

Sensor
R&D



The Mu3e detector



Mu3e physics

